

**IN THE CLAIMS:**

1. (Canceled) Please cancel Claim 1.
2. (Amended) ~~The high-frequency coil device as claimed in claim 1,~~ A high-frequency coil device, comprising:  
a dielectric substrate; and  
a coil formed of a conductive layer embedded in a predetermined coil pattern in the surface of said dielectric substrate, portions of the bottom surface and side surface of said coil being covered by said dielectric substrate, wherein a recess is formed in the surface of said dielectric substrate, and said coil is designed as an aerial wire separated from said dielectric substrate and said recess. has other portions which have a gap between a bottom surface of the coil and the substrate.
3. (Canceled) Please cancel Claim 3.
4. (Original) The high-frequency coil device as claimed in Claim 2, wherein said resin layer is a polyimide layer or a liquid crystal polymer layer.
5. (Canceled) Please cancel Claim 5.
6. (Original) The high-frequency coil device as claimed in claim 4, wherein said plating layer has a multi-layered structure in which a nickel plating layer and a copper plating layer are laminated.
7. (Canceled) Please cancel Claim 7.
8. (Canceled) Please cancel Claim 8.
9. (Canceled) Please cancel Claim 9.